



SOT766-2

Plastic thermal enhanced low profile quad flat package; 176 leads, 0.5 mm pitch, 24 mm x 24 mm x 1.4 mm body

1 June 2018

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP176
Package type industry code	HLQFP176
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	1-4-2014
Manufacturer package code	SOT766

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	23.9	24	24.1	mm
package width	23.9	24	24.1	mm
seated height	1.4	1.5	1.6	mm
package height	1.35	1.4	1.45	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	176	-	A/A



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2. Package outline

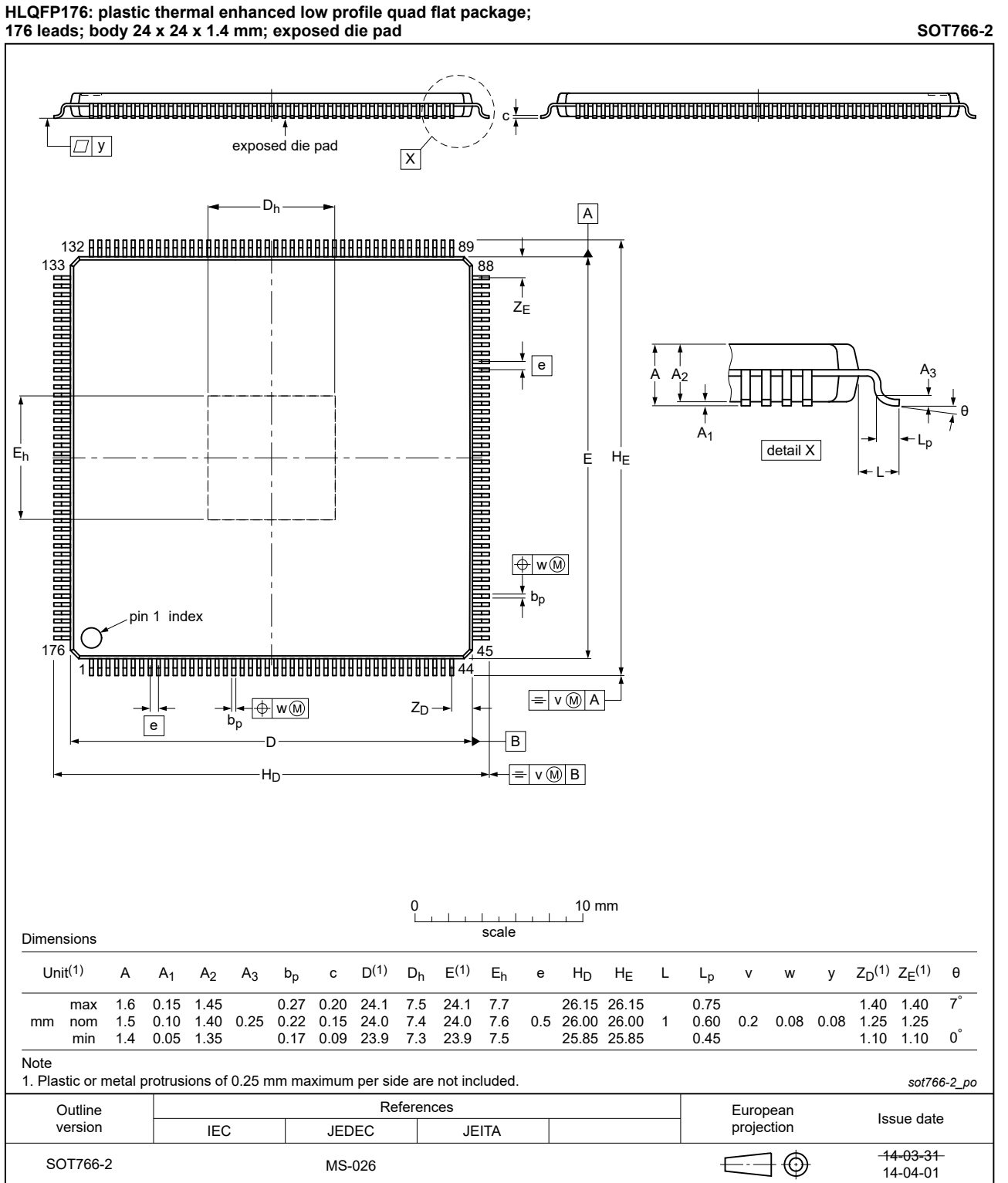


Fig. 1. Package outline HLQFP176 (SOT766-2)

3. Soldering

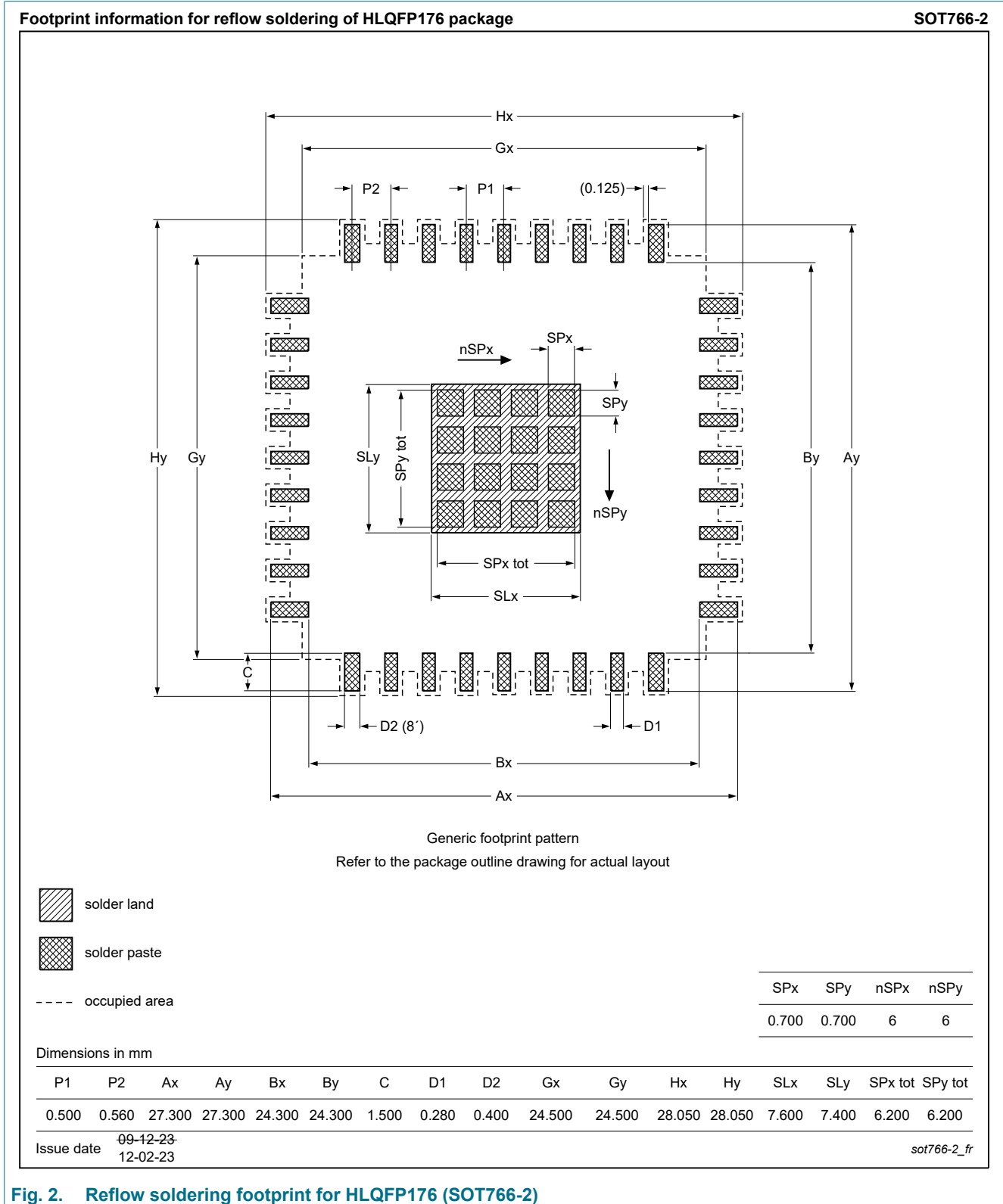


Fig. 2. Reflow soldering footprint for HLQFP176 (SOT766-2)

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4. Legal information

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